INTERNATIONAL CONFERENCE ON 3D IMMERSION 2021
CALL FOR PAPERS

8 DECEMBER 2021
THE EGG - BRUSSELS, BELGIUM

IC3D will be held at The Egg Brussels, located in the heart of the Capital of Belgium and the European Union. In the title of the conference, "immersion", possibly qualified by "3D", refers to the creation of depth and volume, in images and sound, with appropriate input and output means, for virtual reality (VR), augmented reality (AR), mixed reality (MR) and extended reality (XR). The conference covers, among others, the creation and capture of immersive content, novel 3D rendering techniques for ultra-realistic content (including holography) and/or real-time rendering, as well as multi-camera systems and light field compression.

SCOPE
The scope includes all possible signal processing in each conceivable, end-to-end 3D processing chain, e.g., capture of real 3D images and sound, their synthetic generation, pre-processing and scene modelling, as well as coding, transmission, storage, and post-processing for visualization, sound spatialization and other forms of exploitation. IC3D also explores the many applications of 3D immersion, including in industry, engineering, R&D, design, maintenance, science, medicine, psychology, architecture, real estate, defence, communication, advertisement, culture, education, and entertainment.

These aspects will be covered over four thematic sessions:
- Capture and creation of immersive VR/AR/MR/XR content
- Light field coding, mesh and point cloud coding, and transmission
- Real-time 3D rendering techniques
- Ultra-realistic rendering, including holography

CONTEXT AND ACTIVITIES
While IC3D is a self-contained event, it is nevertheless seamlessly integrated into Stereopsia, the World Immersion Forum. This umbrella event includes several components, including IC3D, thematic conferences, an exhibition and an Awards dinner. Stereopsia will take place at The Egg Brussels on 8-10 Dec 2021; information can be found at www.stereopsia.com.
As for all preceding editions, IC3D is expected to be technically co-sponsored by the IEEE Signal Processing Society, and its proceedings to be archived in the IEEE Xplore Digital Library. The Best Paper Award* will be in the form of a prestigious award, handed out on the last day of Stereopsia during an Awards Ceremony.

KEY EVENTS AND DATES
Issuance of the Call for papers: 30 March 2021
Deadline for submitting papers: 1 September 2021
Notification of acceptance/rejection: 15 October 2021
Deadline for submitting camera-ready papers: 15 November 2021
IC3D conference: 8 December 2021
Awards Ceremony: 10 December 2021

Paper reviews are double blind. Moreover, authors/co-authors who belong to the Organizing and/or Program Committee will not participate to the Best Paper Award selection committee.

SUBMISSION LINK
[not available yet]

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